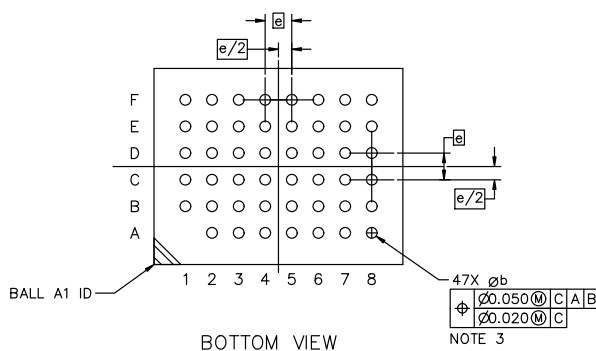
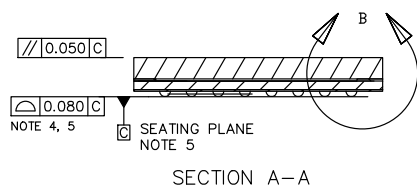
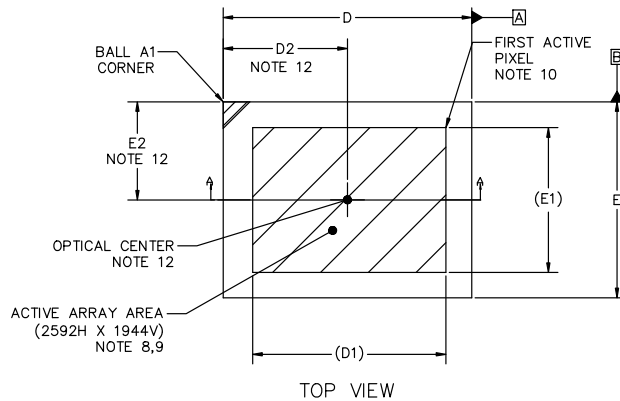

ODCSP47 4.67x3.68x0.63, 0.50P
CASE 570DD
ISSUE A

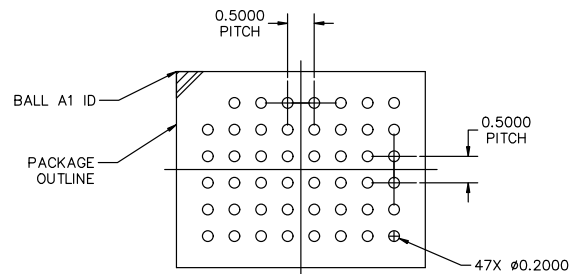
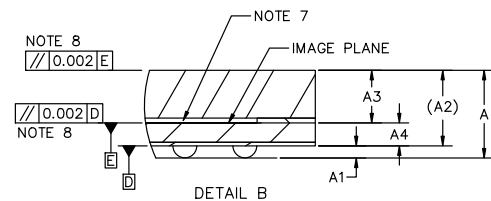
DATE 05 JUN 2025

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.040 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS $\pm 0.1^\circ$.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.034, -0.005).
13. PLAIN COVER GLASS WITHOUT AR COATING.



MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	0.762
A1	0.081	0.101	0.121
A2	0.631 REF		
A3	0.426	0.440	0.454
A4	0.180	0.191	0.202
b	0.184	0.204	0.224
D	4.645	4.670	4.695
D1	3.629 REF		
D2	2.344	2.369	2.394
E	3.657	3.682	3.707
E1	2.722 REF		
E2	1.821	1.846	1.871
e	0.500 BSC		



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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